



2858

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: S. Ohkawa et al. Attorney Docket No.: SUSU121258
Application No.: 10/600,800 Group Art Unit: 2858
Filed: June 19, 2003
Title: SEMICONDUCTOR CHARACTERISTIC EVALUATION APPARATUS

INFORMATION DISCLOSURE STATEMENT

Seattle, Washington 98101

December 4, 2003

TO THE COMMISSIONER FOR PATENTS:

Applicants are aware of the information listed in the attached form that may be material to the prosecution of the above-identified patent application.

1. X A copy of the listed publication is enclosed for the Examiner's use.
2. X Pursuant to 37 C.F.R. § 1.97(b), this Information Disclosure Statement is being filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service in a sealed envelope as first class mail with postage thereon fully prepaid and addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the below date.

Date: 12/4/03

Shannon Hill



INFORMATION CITED BY APPLICANTS THAT MAY BE MATERIAL TO THE
PROSECUTION OF THE SUBJECT APPLICATION

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OTHER INFORMATION
(Including Author, Title, Date, Pertinent Pages, Etc.)

*Examiner Cite
Initial No.

O1 Chen, J.C., et al., "An On-Chip, Interconnect Capacitance Characterization Method With Sub-Femto-Farad Resolution," *Proceedings of the IEEE, International Conference on Microelectronic Test Structures*, Monterey, California, Vol. 10, March 1997, pp. 77-80.

Examiner

Date Considered

*Examiner: Initial if reference considered, whether or not citation is in conformance with M.P.E.P. § 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

JMS:snh